

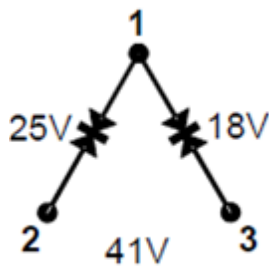
Product Overview

The TQP200002 ESD protection device is fabricated in GaAs MESFET technology and has been especially developed for high frequency applications. It delivers bi-directional protection with very low leakage currents and extremely low capacitance. It is ideally suited for cellular handsets, cordless phones, and broadband applications like CATV set top boxes and LNBS.



1.2 mm x 1.5 mm SMT

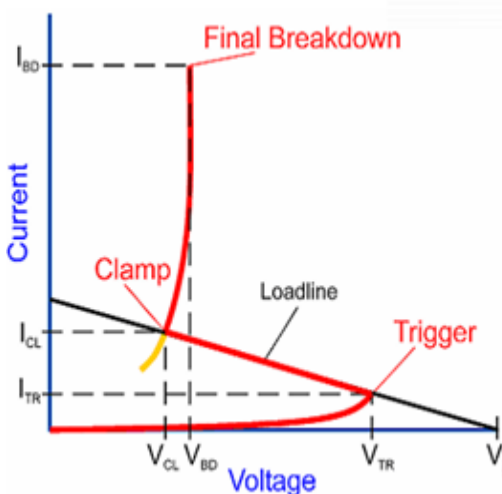
Functional Block Diagram



Key Features

- Snap-Back ESD protection
- Low clamp voltages 15 or 30 V
- Low trigger voltages 18, 25, or 41 V
- Two bidirectional protection lines
- Fast response time: under 1 ns
- Low capacitance: 0.22 pF
- Thin Small Leadless SMT Package (A=1.8 mm²)

Snap Back Characteristics



Applications

- Cellular Handsets
- Cordless Phone
- LNBS
- CATV set top boxes

Ordering Information

| Part Number | Description |
|-------------|---------------------------------|
| TQP200002 | 13-inch reel with 10,000 pieces |
| TQP200002SR | 7-inch reel with 100 pieces |

Absolute Maximum Ratings

| Parameter | Rating |
|--|----------------|
| Supply Voltage (V_{DD}) | +25 V |
| Total Power Dissipation | +600 mW |
| IEC 61000-4-2 Air Discharge | +3000 V |
| IEC 61000-4-2 Contact Discharge | +3000 V |
| JEDEC Human Body Model (HBM) | +8000 V |
| Storage Temperature Range | -65 to +150 °C |
| Operating Temperature Range | -40 to +105 °C |
| Maximum Junction Temperature (for >10 ⁶ hours MTTF) | +160 °C |

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability.

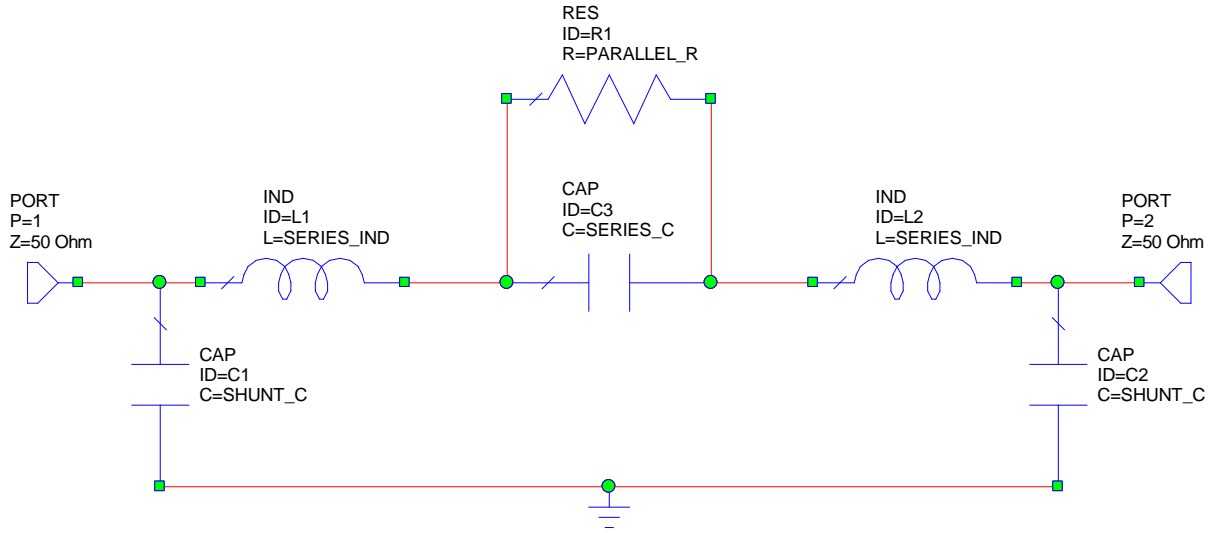
Electrical Specifications

| Parameter | Condition ⁽¹⁾ | Min | Typ | Max | Unit |
|---------------------------------|--------------------------|-----|------|-----|------|
| Supply Voltage (V_{D13}) | | -7 | | +7 | V |
| Supply Voltage (V_{D12}) | | -7 | | +7 | V |
| Supply Voltage (V_{D23}) | | -17 | | +17 | V |
| Trigger Voltage (V_1) | P1, 3 | +13 | +18 | +23 | V |
| Clamp Voltage (V_{C11}) | P1, 3 | +10 | +15 | +20 | V |
| Leakage Current (I_{leak1}) | 1 V | | +20 | | nA |
| Leakage Current (I_{leak1}) | 15 V | | +500 | | nA |
| Capacitance (C_1) | 1 V, 10 MHz | | +290 | | fF |
| Trigger Voltage (V_2) | P1, 2 | +20 | +25 | +30 | V |
| Clamp Voltage (V_{C12}) | P1, 2 | +10 | +15 | +20 | V |
| Leakage Current (I_{leak2}) | 1 V | | +20 | | nA |
| Leakage Current (I_{leak2}) | 15 V | | +500 | | nA |
| Capacitance (C_2) | 1 V, 10 MHz | | +290 | | fF |
| Trigger Voltage (V_3) | P2, 3 | +31 | +41 | +46 | V |
| Clamp Voltage (V_{C13}) | P2, 3 | +20 | +30 | +40 | V |
| Leakage Current (I_{leak3}) | 1 V | | +15 | | nA |
| Leakage Current (I_{leak3}) | 15 V | | +300 | | nA |
| Capacitance (C_3) | 1 V, 10 MHz | | +220 | | fF |

Notes:

1. Typical performance at these conditions: Temp = +25 °C, 75 Ω system

Device Characterization Data



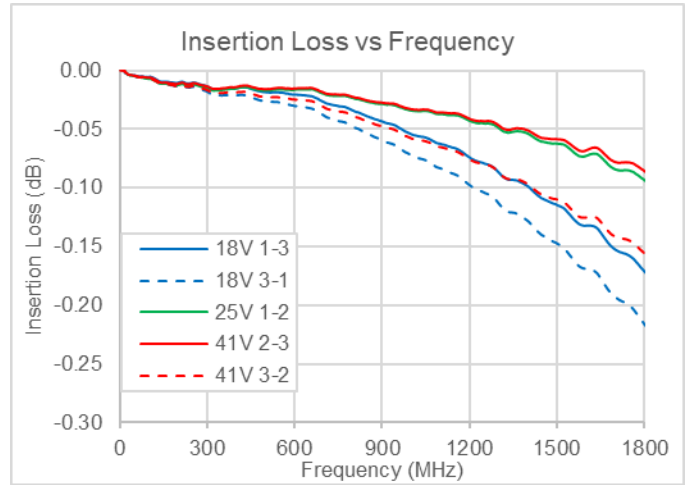
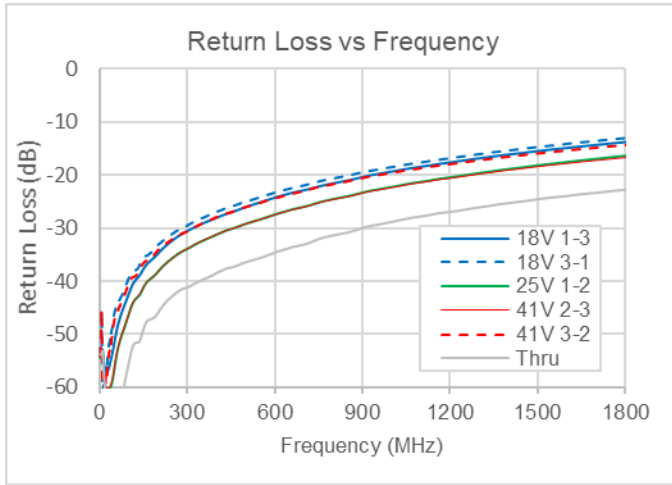
| Pin 2 to Pin 3 Small Signal Element | Value | Unit |
|-------------------------------------|-------|------|
| Series_C | 0.22 | pF |
| Shunt_C_In | 0.08 | pF |
| Shunt_C_Out | 0.01 | pF |
| Series_Ind | 0.20 | nH |
| Parallel_R | 230 | MΩ |

Notes:

1. Values of input and output shunt capacitances are dependent upon the board material and the board pad sizes and will be layout dependent.

| Trigger Voltage | Unit | V1 = 18 V | V2 = 25 V | V3 = 41 V |
|--------------------|------|-----------|-----------|-----------|
| Insertion Loss | dB | 0.3 | 0.25 | 0.25 |
| Input Return Loss | dB | 19 | 21 | 21 |
| Output Return Loss | dB | 19 | 21 | 21 |

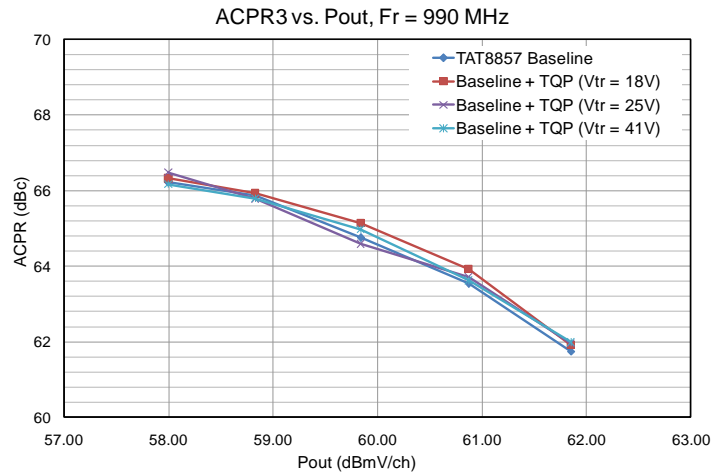
Typical Performance: 5MHz – 1800MHz



Notes:

1. Plots show effects of diode orientation from PCB trace to ground. Ex: 1-3 shows RF applied to pin 1 with pin 3 connected to ground.
2. Insertion Loss plot is loss compensated to remove the effect of the PCB.

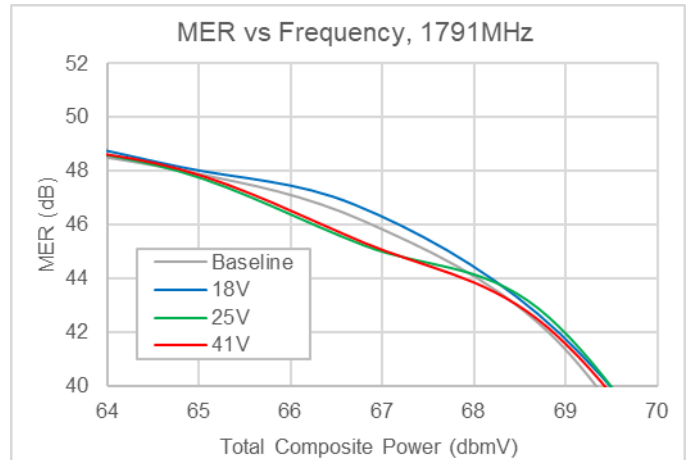
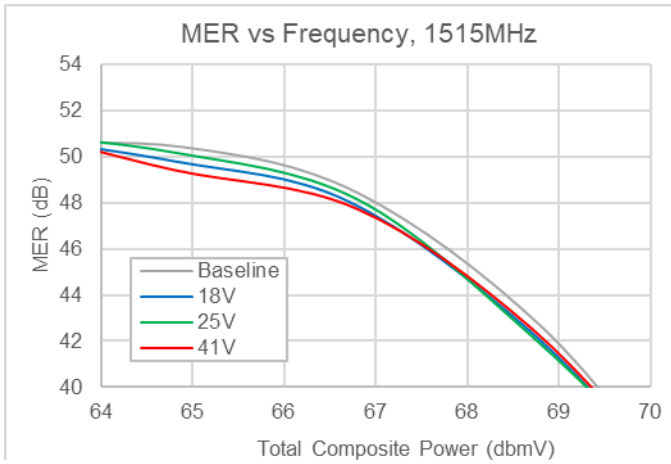
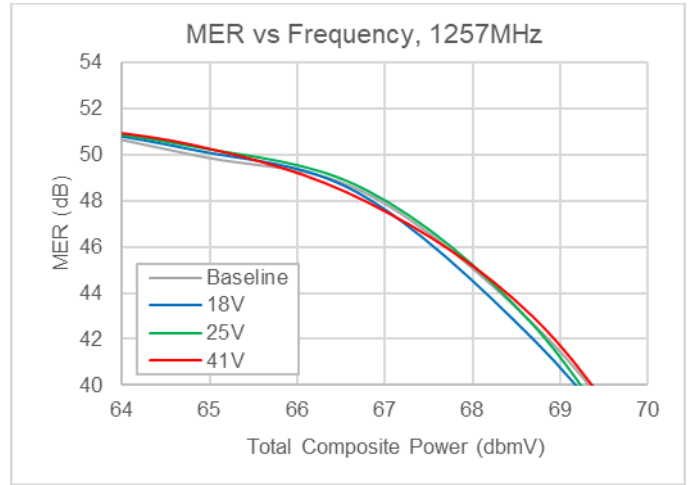
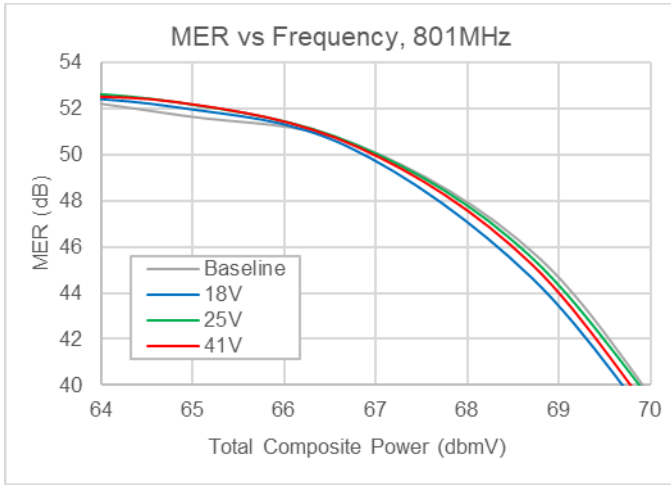
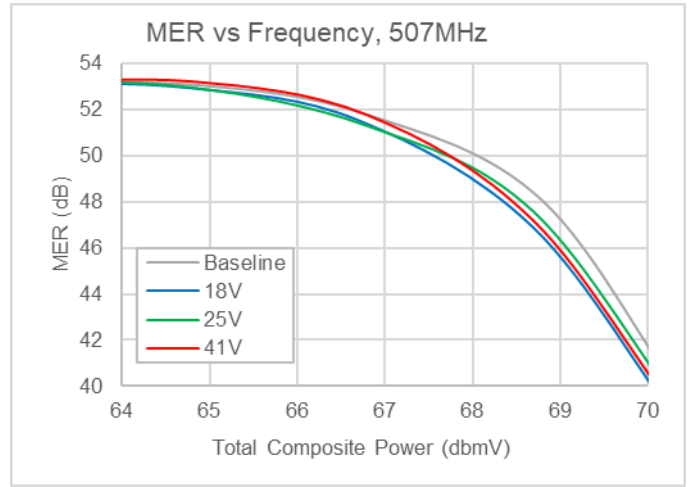
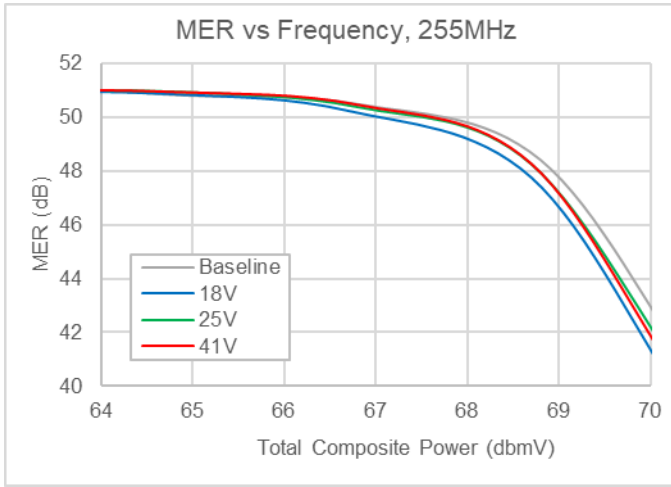
Distortion Performance: ACPR



Notes:

1. ACPR data was taken against a baseline obtained for the TAT8857 at 990 MHz.
2. Channel plan: 4 combined channels, 256 QAM modulation per DOCSIS 3.0
3. ACPR3: -6 MHz from channel block edge to 12 MHz from channel block edge.

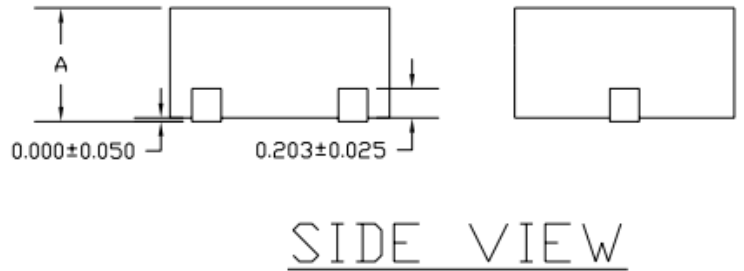
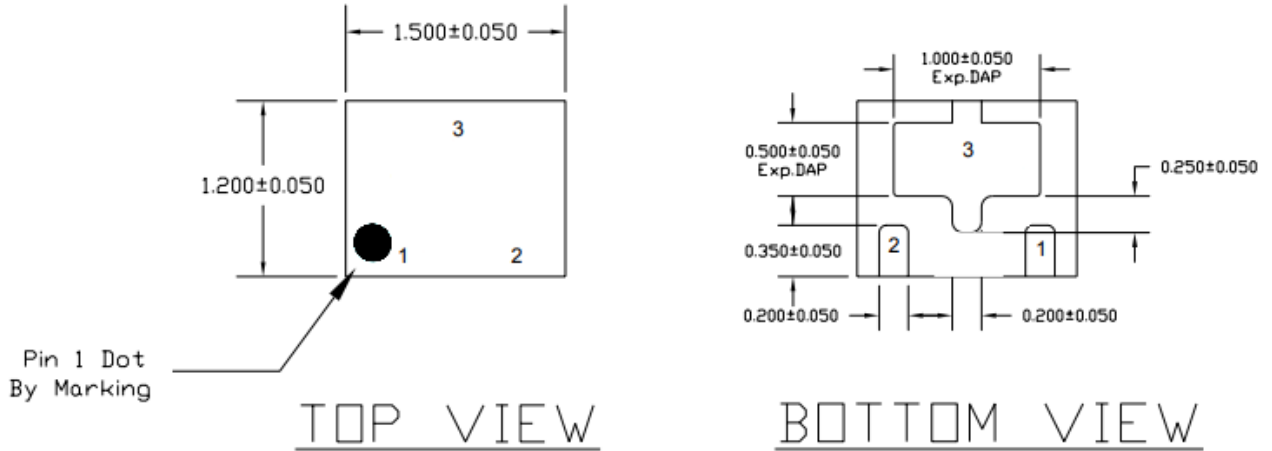
Distortion Performance; 1.8GHz MER



Notes:

1. Distortion data was taken against baselines obtained for the QPA8840 with the TQP200002 added to the output as noted.
2. 255 – 1791MHz, 256 channels SC-QAM, 10dB tilt, 0dB offset. Source corrected, maximum correction 4.3dB.

Package Outline



| | | |
|---|------|-------|
| A | | TSLP |
| | MAX. | 0.800 |
| | NOM. | 0.750 |
| | MIN. | 0.700 |

ALL MEASUREMENT IN (MM)

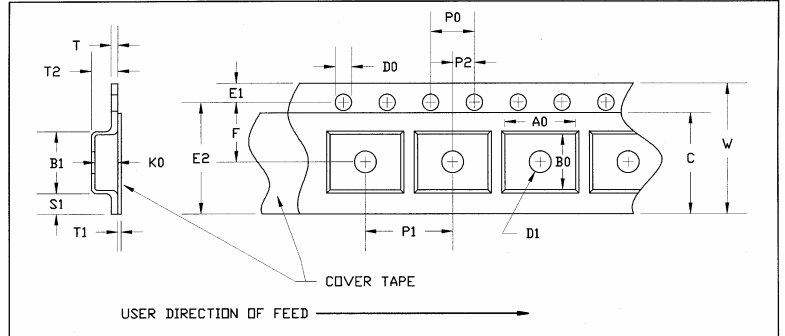
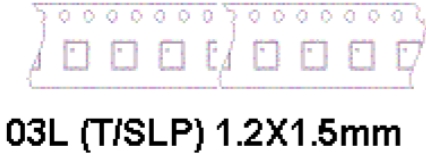
Package Marking



WHITE INK OR LASER MARK.

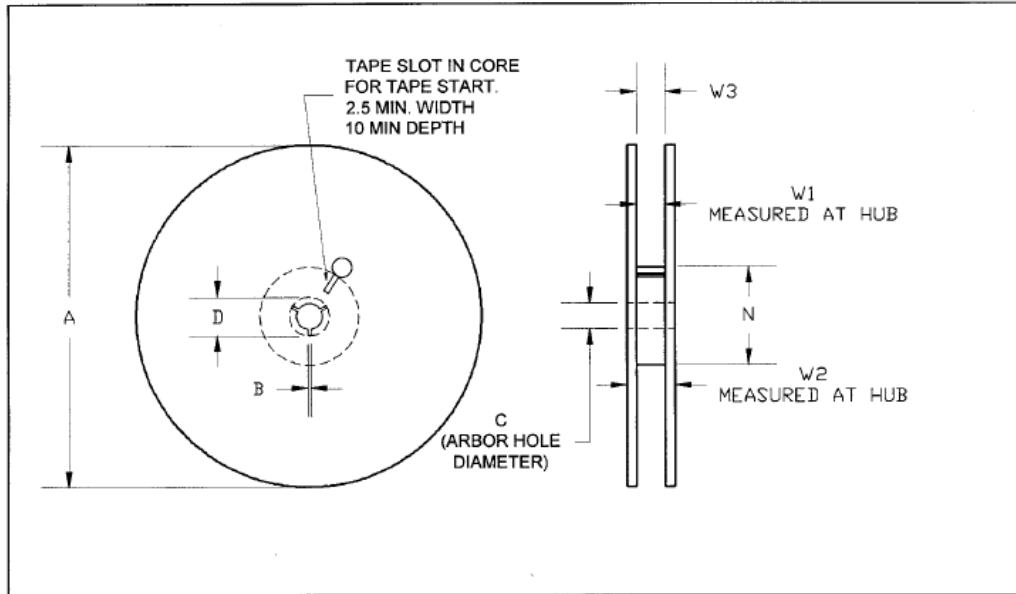
Line 1: XX = Last 2 digits of Qorvo assembly lot number

Tape and Reel Information



| Part | Feature | Symbol | Size (in) | Size (mm) |
|-----------------------------|-----------------------|--------|-----------|-----------|
| Cavity | Length | A0 | 0.053 | 1.35 |
| | Width | B0 | 0.068 | 1.75 |
| | Depth | K0 | 0.040 | 1.02 |
| | Pitch | P1 | 0.157 | 4.00 |
| Distance Between Centerline | Cavity to Perforation | P2 | 0.079 | 2.00 |
| | Length Direction | | | |
| | Cavity to Perforation | F | 0.138 | 3.50 |
| | Width Direction | | | |
| Cover Tape | Width | C | 0.213 | 5.40 |
| Carrier Tape | Width | W | 0.315 | 8.00 |

Tape and Reel Information



| T/SLP | | | 13" REEL | |
|--------|----------------------|--------|-----------|-----------|
| PART | FEATURE | SYMBOL | SIZE (in) | SIZE (mm) |
| FLANGE | DIAMETER | A | 12.992 | 330.0 |
| | THICKNESS | W2 | 0.567 | 14.4 |
| | SPACE BETWEEN FLANGE | W1 | 0.331 | 8.4 |
| HUB | OUTER DIAMETER | N | 3.937 | 100.0 |
| | ARBOR HOLE DIAMETER | C | 0.512 | 13.0 |
| | KEY SLIT WIDTH | B | 0.059 | 1.5 |
| | KEY SLIT DIAMETER | D | 0.795 | 20.2 |

Handling Precautions

| Parameter | Rating | Standard |
|----------------------------------|----------|------------------------|
| ESD – Human Body Model (HBM) | Class 3B | ANSI/ESDA/JEDEC JS-001 |
| ESD – Charged Device Model (CDM) | Class C3 | ANSI/ESDA/JEDEC JS-002 |
| MSL – Moisture Sensitivity Level | Level 1 | IPC/JEDEC J-STD-020 |



Caution!
ESD-Sensitive Device

RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- PFOS Free
- SVHC Free



Solderability

Compatible with both lead-free (260 °C max. reflow temp.) and tin/lead (245 °C max. reflow temp.) soldering processes. Solder profiles available upon request.

Contact plating: Matte Sn

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

Tel: 1-844-890-8163

Web: www.qorvo.com

Email: customer.support@qorvo.com

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